



**Assembly Notes:**

Built on PCB: PMP30189 Rev\_B

Do Not Populate: C1, C2, C12, C15, R17, Q2, H1

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Orderable: NA	Designed for: Public Release	Mod. Date: 7/17/2017
TID #: 0	Project Title: 27V...29Vin to 12V@6.5A Synch. Buck with OVP	Sheet Title: 27V...29Vin to 12V@6.5A Synch. Buck with OVP
Number: PMP30301	Rev: A	Assembly Variant: [No Variations]
SW Rev: Version control disabled	Drawn By: R. Scibilla	File: PMP30301 Rev. A Schematic.SchDoc
Engineer: R. Scibilla	Contact: http://www.ti.com/support	Sheet: 1 of 1



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